

LARGE AREA PRINTING METHOD FOR INTEGRATING DEVICE AND CIRCUIT COMPONENTS

CROSS REFERENCE TO RELATED APPLICATIONS

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This application claims benefit of United States Provisional Application No.

60/398,390 filed on July 25, 2002, which is incorporated herein by reference in its entirety.

This application is also related to the copending and commonly assigned patent application documents entitled "Oriented Self-Location of Microstructures with Alignment Structures,"

Provisional Application No. ~~Serial No. 60/490,193~~ (Attorney Docket No. 620193-9) and "Self-Location Method
10 ~~Provisional Application~~ and Apparatus," ~~Serial No. 60/490,194~~ (Attorney Docket No. 619932-8), which are all
filed of even date herewith. The contents of these related applications are hereby
incorporated by reference herein.

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FIELD

The present invention relates to fabricating integrated electronic systems and, more particularly, to a method for fabricating arbitrarily configured arrays of devices or circuit modules on host circuits or substrates.

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BACKGROUND

Increasingly complex integrated electronic and optoelectronic systems require larger
25 numbers of integrated circuits and devices to implement increasingly complex system functions. However, to achieve cost and weight goals, it is preferred that these integrated systems be implemented with as few separate device structures as possible. One approach is to fabricate all of the integrated circuits and devices on a single wafer or portion of a wafer, which provides the structural base for the system and minimizes the interconnect distances